

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

71711-8

Application Number

To be assigned

Applicant(s)

Tai Chung CHAI et al.

Filing Date

Concurrently Herewith

Group Art Unit

To be assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
CC		4,924,291		Lesk et al.	—	—	

JCS64 U.S. PTO
09/497421
02/07/00

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

CC		Umehara, Norito et al., S-Pad Implementation; Total Plastic Package Crack Solution for Non-Moisture Sensitive Package, New Package Development, Texas Instruments Japan, Ltd., Hi j. i. Plant, 4260 takao, Kawasaki, Hiji-machi, Hayami-gun Oita Japan 879-15
U	~	Ganesan, Gans S. et al., Level I CrackFree Plastic Packaging Technology, Motorola Inc.. Semiconductor Products Sector, 2100 E. Elliot Road, Tempe, AZ 85284

EXAMINER

[Signature]

DATE CONSIDERED

7-11-01

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INFORMATION DISCLOSURE CITATION*(Use several sheets if necessary)*

Docket Number (Optional)

928/71711-2/8

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INITIALOTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*

CC

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Nakazawa, Tsutomu et al., A Novel Structure to Realize Crack-Free Plastic Packages During Reflow Soldering Process-Development of Chip Side Support (CSS) Package, IEEE Transactions on Components Packaging and Manufacturing Technology - Part C, Vol. 19, No. 1, January 1996, pp. 61-69.

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Chan, K. C. and Chai, T. C., Type II Popcorn Failure Analysis in Plastic Encapsulated IC Package Using Scanning Acoustic Microscopy and Cross-Sectioning (not yet published)

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CHA, Ki-Bon et al.; Ultra-Thin and Crack-Free Bottom Leaded Plastic (BLP) Package Design; LG Semicon (Gold Star) Package R&D Center, Cheongju, Korea 360-480 0569-5503/95/0000 © 1995 IEEE

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1-11-01

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